



## Material Content Data Sheet



<b>Sales Product Name</b>		BTS711L1		<b>Issued</b>		19. July 2018		
<b>MA#</b>		MA001205944						
<b>Package</b>		PG-DSO-20-59		<b>Weight*</b>		499.35 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	9.157	1.83	1.83	18338	18338
leadframe	inorganic material	phosphorus	7723-14-0	0.042	0.01		85	
	non noble metal	zinc	7440-66-6	0.169	0.03		339	
	non noble metal	iron	7439-89-6	3.388	0.68		6785	
wire	non noble metal	copper	7440-50-8	137.580	27.55	28.27	275517	282726
	noble metal	gold	7440-57-5	1.932	0.39	0.39	3868	3868
	encapsulation	organic material	carbon black	1333-86-4	0.677	0.14		1356
encapsulation	plastics	epoxy resin	-	31.137	6.24		62355	
	inorganic material	silicondioxide	60676-86-0	306.630	61.40	67.78	614058	677769
leadfinish	non noble metal	tin	7440-31-5	2.746	0.55	0.55	5499	5499
plating	noble metal	silver	7440-22-4	3.476	0.70	0.70	6962	6962
glue	plastics	epoxy resin	-	0.423	0.08		847	
	noble metal	silver	7440-22-4	1.993	0.40	0.48	3991	4838
*deviation	< 10%				Sum in total:	100.00		1000000

### Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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